Contact Name Title - Contact Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product Enviro Compliance Title - Representative Phone - Contact* Phone - Contact* Product-Env-Stewards@onsemi.com Phone - Representative* Email - Representative* Email - Representative* Product-Env-Stewards Product-Env-Stewards@onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with local level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
Company name* Company unique ID Unique ID Authority Response Date* 2025-05-11 2025-05-11 Contact Name Title - Contact* Phone - Contact* Product-Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product-Env-Stewards Produ	752-21.1											als and Mfg	g Informati	on	
Insemi ontact Name Title - Contact Product Env-Stewards Uthorized Representative* Title - Representative Title - Representative Product Enviro Compliance Uthorized Representative* Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards©onsemi.com Product-Env-Stewards©onsemi.com Product-Env-Stewards©onsemi.com Product-Env-Stewards©onsemi.com Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U Annufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed OU Alloy 1 260 C 30 seconds 3	upplier Informa	ation													
Title - Contact Name Product Env-Stewards Product Enviro Compliance NA Product Env-Stewards Product Enviro Compliance NA Product-Env-Stewards Product-Env-St	Company name* Company unique ID					Unique ID Authority				Response Date*					
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Product Enviro Compliance Requester Item Number Requester	ontact Name			Title - Contact			I	Phone - Contact*				Email - Contact*			
Product Envisor Compliance Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM U FAN7380MX-OP Half bridge gate driver 2025-05-11 TH2 83.484 mg Effective Date Fand Requester Item Number Manufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Te	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			I	Phone - Representative*			Email - Representative*					
FAN7380MX-OP Half bridge gate driver 2025-05-11 TH2 83.484 mg Each of the comments of the comments of the comments of the comments of the comment of the com	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Manufacturing Proccess Information Terminal Plating / Grid Array Material Matte Tin (Sn) - annealed CU Alloy Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 C 30 Seconds Seconds	Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	N	Manufacturing Site	W	eight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 C Somments			FAN7380)MX-OP	Half bridge gate dri	iver		2025-05-11		Т	TH2	83	3.484	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 comments				arminal Paga	Alloy	etd ogo mei	Poting	Dook Prog	oss Pody To	maratur	May Time at Peak	Tomporatu	ra Numb	or of Poflow Cur	Jac
omments					Alloy J-3	S1D-020 MSL	Kaung		ess body 16					er of Reflow Cyc	ties
	•	i (Sii) • aimeaieu	C	Alloy	1			200		IC	30	second	s 3		
ver 1 - maximum ume at peak temperature during soldering is 10-50 seconds		me at neels temperature	during cal	domina is 10.	20 seconds										
or more information regarding material composition please refer to page 3		·													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.16	mg	Supplier	Silicon (Si)	7440-21-3		2.16	mg
Die Attach	1.144	mg		Epoxy resin	proprietary data		0.1487	mg
			Supplier	Silver (Ag)	7440-22-4		0.4004	mg
			Supplier	Acrylic resins	Proprietary Data		0.1945	mg
			Supplier	Aluminum (Al)	7429-90-5		0.4004	mg
Lead Frame	31.136	mg	Supplier	Silver (Ag)	7440-22-4		0.6227	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0374	mg
			Supplier	Iron (Fe)	7439-89-6		0.7317	mg
			Supplier	Copper (Cu)	7440-50-8		29.7349	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0093	mg
Mold Compound-Black	45.29	mg	Supplier	4,4'-Bis(2,3-epoxypropoxy)-3,3',5,5'-tetramethylbiphenyl	85954-11-6		2.0381	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.6668	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		1.3587	mg
Plating	3.44	mg	Supplier	Tin (Sn)	7440-31-5		3.44	mg
Wire Bond	0.314	mg	Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.3077	mg